

机芯科技  
HUTCHIP

**HC3134KW**

**20V N-Channel MOSFET**

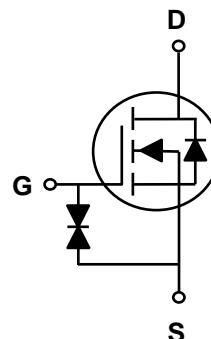
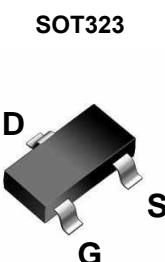
### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### Features

$V_{DS}$	20V
$I_D$ (at $V_{GS}=4.5V$ )	0.5A
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	220m $\Omega$ (Typ)

ESD Protected Up to 2.0KV (HBM)



### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous	$I_D$ (TC=25°C)	0.5	A
	$I_D$ (TC=70°C)	0.4	A
Drain Current – Pulsed	$I_{DM}$	3.3	A
Maximum Power Dissipation	$P_D$	0.18	W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C
Thermal Characteristics			
Parameter	Symbol	Typ	Max
Thermal Resistance junction-to-solder point	$R_{\theta Jc}$		40
Thermal Resistance junction-to-Ambient	$R_{\theta JA}$		830

## Electrical Characteristics (TJ=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V$			1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$			$\pm 10$	$\mu A$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.3	0.7	1.2	V
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=4.5V, I_D=0.5A$		220	300	$m\Omega$
		$V_{GS}=2.5V, I_D=0.4A$		290	400	$m\Omega$
		$V_{GS}=1.8V, I_D=0.2A$		420	700	$m\Omega$
$I_S$	Maximum Body-Diode Continuous Current				0.5	A
<b>DYNAMIC PARAMETERS</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=10V, V_{GS}=0V, F=1.0MHz$		56		pF
$C_{oss}$	Output Capacitance			20		pF
$C_{rss}$	Reverse Transfer Capacitance			2.5		pF
<b>SWITCHING PARAMETERS</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{GS}=4.5V$ $V_{DS}=10V$ $R_G=25\Omega$ $I_D=0.5A$		2		nS
$t_r$	Turn-on Rise Time			18.8		nS
$t_{d(off)}$	Turn-Off Delay Time			10		nS
$t_f$	Turn-Off Fall Time			23		nS
$Q_g$	Total Gate Charge	$V_{DS}=10V, I_D=0.5A, V_{GS}=4.5V$		1		nC
$Q_{gs}$	Gate-Source Charge			0.28		nC
$Q_{gd}$	Gate-Drain Charge			0.2		nC
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_{SD}=1A$		0.70	1.3	V

Note:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

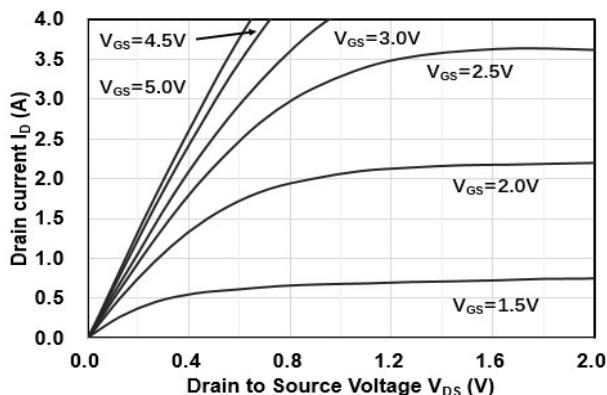


Figure1. Output Characteristics

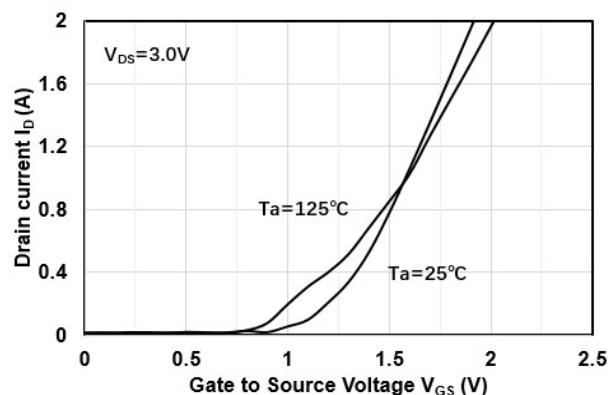


Figure2. Transfer Characteristics

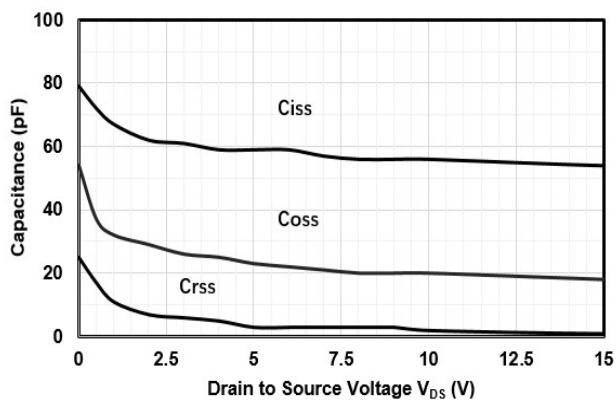


Figure3. Capacitance Characteristics

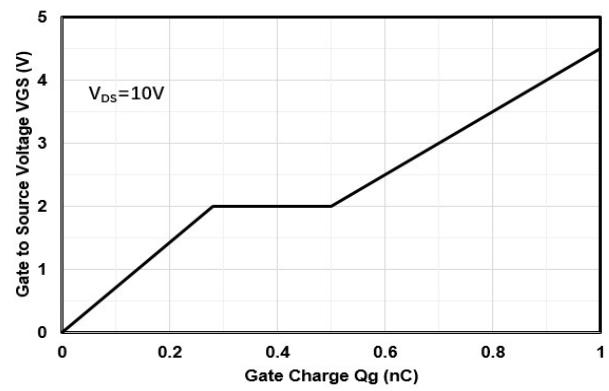


Figure4. Gate Charge

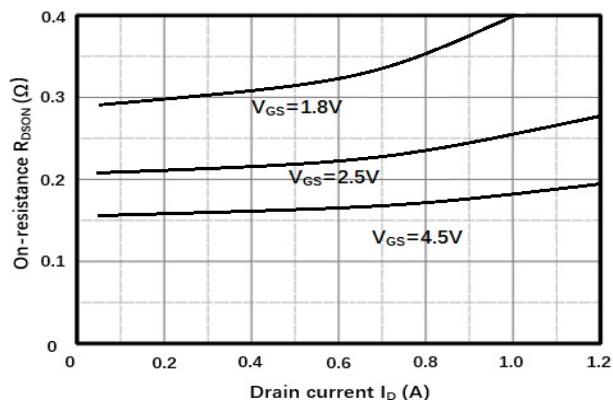


Figure5. Drain-Source on Resistance

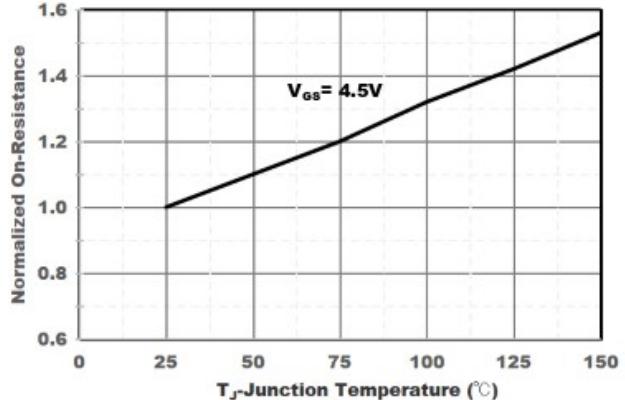


Figure6. Drain-Source on Resistance

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

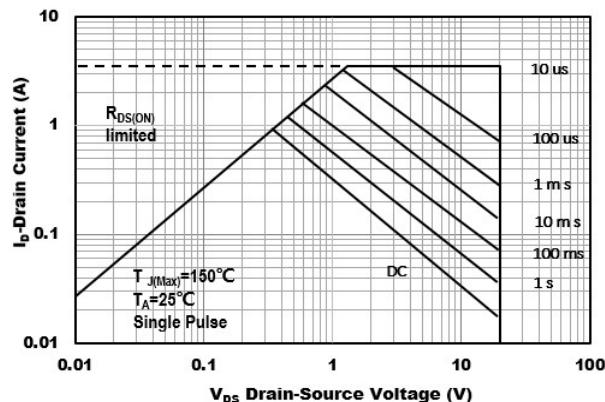


Figure 7. Safe Operation Area

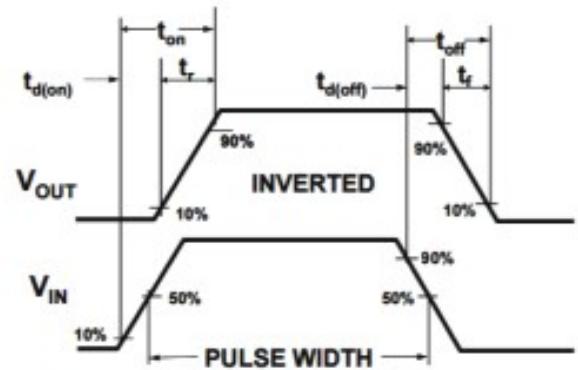
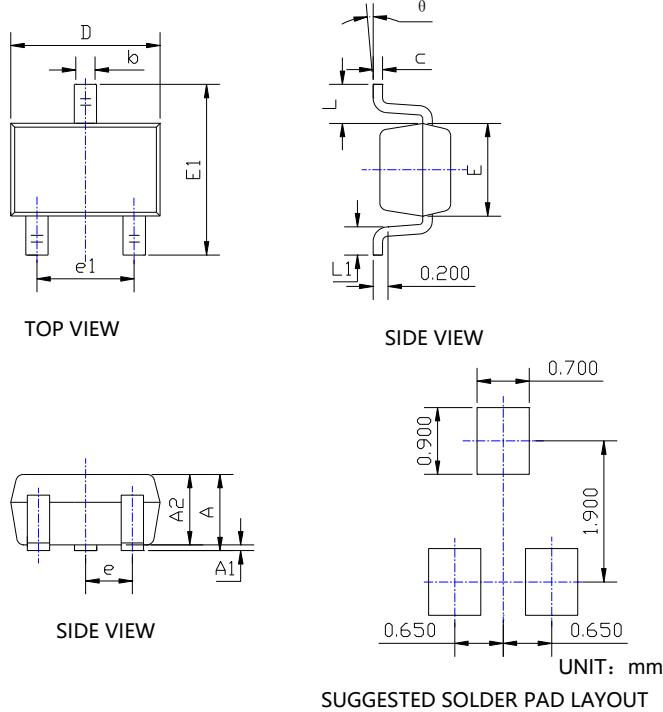


Figure 8. Switching wave

## SOT323 PACKAGE INFORMATION



SYMBOL	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.043	0.900	1.100
A1	0.000	0.004	0.000	0.100
A2	0.035	0.039	0.900	1.000
b	0.006	0.016	0.150	0.400
c	0.004	0.010	0.100	0.250
D	0.071	0.087	1.800	2.200
E	0.045	0.053	1.150	1.350
E1	0.085	0.096	2.150	2.450
e	0.026 TYP		0.650 TYP	
e1	0.047	0.055	1.200	1.400
L	0.021 REF		0.525 REF	
L1	0.010	0.018	0.260	0.460
theta	0°	8°	0°	8°

### NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.